Speed Grades

		Optimized for Lowest C (1.0V, 0.9V)	ost and Lowest Power A	Applications			
	Part Number	XC7A15T	XC7A35T	XC7A50T	XC7A75T	XC7A100T	XC7A200T
Logic Resources	Logic Cells	16,640	33,280	52,160	75,520	101,440	215,360
	Slices	2,600	5,200	8,150	11,800	15,850	33,650
	CLB Flip-Flops	20,800	41,600	65,200	94,400	126,800	269,200
Memory Resources	Maximum Distributed RAM (Kb)	200	400	600	892	1,188	2,888
	Block RAM/FIFO w/ ECC (36 Kb each)	25	50	75	105	135	365
	Total Block RAM (Kb)	900	1,800	2,700	3,780	4,860	13,140
Clock Resources	CMTs (1 MMCM + 1 PLL)	5	5	5	6	6	10
I/O Resources	Maximum Single-Ended I/O	250	250	250	300	300	500
	Maximum Differential I/O Pairs	120	120	120	144	144	240
Embedded Hard IP Resources	DSP Slices	45	90	120	180	240	740
	PCIe® Gen2 ⁽¹⁾	1	1	1	1	1	1
	Analog Mixed Signal (AMS) / XADC	1	1	1	1	1	1
	Configuration AES / HMAC Blocks	1	1	1	1	1	1
	GTP Transceivers (6.6 Gb/s Max Rate) ⁽²⁾	4	4	4	8	8	16
	Commercial	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2

	Package ^{(3), (4)}	Dimensions (mm)	Available User I/O: 3.3V SelectIO™ HR I/O (GTP Transceivers)							
	CPG236	10 x 10	106 (2)	106 (2)	106 (2)					
	CSG324	15 x 15	210 (0)	210 (0)	210 (0)	210 (0)	210 (0)			
	CSG325	15 x 15	150 (4)	150 (4)	150 (4)					
	FTG256	17 x 17	170 (0)	170 (0)	170 (0)	170 (0)	170 (0)			
	SBG484	19 x 19						285 (4)		
Footprint Compatible	FGG484	23 x 23	250 (4)	250 (4)	250 (4)	285 (4)	285 (4)			
	FBG484	23 x 23						285 (4)		
Footprint Compatible	FGG676	27 x 27				300 (8)	300 (8)			
	FBG676	27 x 27						400 (8)		
	FFG1156	35 x 35						500 (16)		

-2L, -3

-1, -2, -1L

XMP086 (v4.6)

-2L, -3

-1, -2, -1L

CPG: 0.5 mm Wire-bond chip-scale; CSG: 0.8 mm Wire-bond chip-scale; FTG: 1.0 mm Wire-bond fine-pitch; SBG: 0.8 mm Lidless flip-chip; FGG: 1.0 mm Wire-bond fine-pitch; FBG 1.0 mm Lidless flip-chip; FFG: 1.0 mm Flip-chip fine-pitch

Notes: 1. Supports PCI Express Base 2.1 specification at Gen1 and Gen2 data rates.

Extended

Industrial

- 2. Information represents the maximum number of transceivers available. Please note that the majority of devices are available without transceivers. See the Package section of this table for details.
- 3. Leaded package option available for all packages.
- 4. Device migration is available within the Artix-7 family for like packages but is not supported between other 7 series families.

-2L, -3

-1, -2, -1L

Artix®-7 FPGAs

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